#### FEATURES

- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Sub-1-V Operable
- Max t<sub>pd</sub> of 1.7 ns at 1.8 V
- Low Power Consumption, 20-μA Max I<sub>cc</sub>
- ±8-mA Output Drive at 1.8 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## **DESCRIPTION/ORDERING INFORMATION**

This octal bus transceiver is operational at 0.8-V to 2.7-V  $V_{CC}$ , but is designed specifically for 1.65-V to 1.95-V  $V_{CC}$  operation.

The SN74AUC245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so the buses are effectively isolated.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

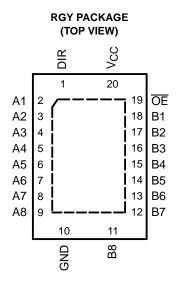
#### **ORDERING INFORMATION**

T <sub>A</sub>	PACK	AGE <sup>(1)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
–40°C to 85°C	QFN – RGY	Tape and reel	SN74AUC245RGYR	MS245	
-40 C 10 65 C	VFBGA – GQN	Tape and reel	SN74AUC245GQNR	MS245	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



## SN74AUC245 OCTAL BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCES419A-JANUARY 2003-REVISED MARCH 2005



#### GQN PACKAGE (TOP VIEW) 1 2 3 4 0

Α

в С

D

Е

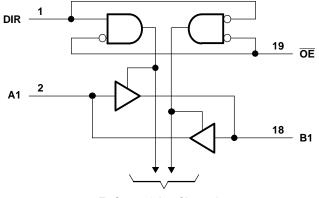
#### **TERMINAL ASSIGNMENTS**

	1	2	3	4
Α	A1	DIR	V <sub>CC</sub>	OE
В	A3	B2	A2	B1
С	A5	A4	B4	B3
D	A7	B6	A6	B5
Е	GND	A8	B8	B7

#### **FUNCTION TABLE**

INP	UTS	
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Х	Isolation

### LOGIC DIAGRAM (POSITIVE LOGIC)



To Seven Other Channels

Pin numbers shown are for the RGY package.

# Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5	3.6	V
VI	Input voltage range <sup>(2)</sup>	-0.5	3.6	V	
Vo	Voltage range applied to any output in the high	n-impedance or power-off state <sup>(2)</sup>	-0.5	3.6	V
Vo	Output voltage range <sup>(2)</sup>	-0.5	V <sub>CC</sub> + 0.5	V	
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
I <sub>O</sub>	Continuous output current			±20	mA
	Continuous current through V <sub>CC</sub> or GND			±100	mA
0		GQN package <sup>(3)</sup>		78	
$\theta_{JA}$	Package thermal impedance	RGY package <sup>(4)</sup>		37	°C/W
T <sub>stg</sub>	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

The package thermal impedance is calculated in accordance with JESD 51-7.

(4) The package thermal impedance is calculated in accordance with JESD 51-5.

## **Recommended Operating Conditions**<sup>(1)</sup>

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		0.8	2.7	V
		V <sub>CC</sub> = 0.8 V	V <sub>CC</sub>	3.6	
VIH	High-level input voltage	V <sub>CC</sub> = 1.1 V to 1.95 V	$0.65 \times V_{CC}$	3.6	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7	3.6	
		V <sub>CC</sub> = 0.8 V		0	
V <sub>IL</sub>	Low-level input voltage	$V_{CC} = 1.1 \text{ V to } 1.95 \text{ V}$	0	$0.35 \times V_{CC}$	V
		$V_{CC}$ = 2.3 V to 2.7 V	0	0.7	
V		Active state	0	V <sub>CC</sub>	V
Vo	Output voltage	3-state	0	3.6	V
		V <sub>CC</sub> = 0.8 V		-0.7	
	High-level output current	V <sub>CC</sub> = 1.1 V		-3	
I <sub>OH</sub>		V <sub>CC</sub> = 1.4 V		-5	mA
	V <sub>CC</sub> = 1.65 V			-8	
		$V_{CC} = 2.3 V$		-9	
		V <sub>CC</sub> = 0.8 V		0.7	
		V <sub>CC</sub> = 1.1 V		3	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.4 V		5	mA
		V <sub>CC</sub> = 1.65 V		8	
		V <sub>CC</sub> = 2.3 V		9	
$\Delta t / \Delta v$	Input transition rise or fall rate	· · ·		20	ns/V
T <sub>A</sub>	Operating free-air temperature		-40	85	°C

 All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

## **SN74AUC245 OCTAL BUS TRANSCEIVER** WITH 3-STATE OUTPUTS

SCES419A-JANUARY 2003-REVISED MARCH 2005

### **TEXAS** STRUMENTS www.ti.com

#### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMET	TEST CONDITIONS	V <sub>cc</sub>	MIN TYP <sup>(1)</sup> MAX	UNIT
	I <sub>OH</sub> = -100 μA	0.8 V to 2.7 V	V <sub>CC</sub> – 0.1	
	I <sub>OH</sub> = -0.7 mA	0.8 V	0.55	
M	$I_{OH} = -3 \text{ mA}$	1.1 V	0.8	V
V <sub>OH</sub>	$I_{OH} = -5 \text{ mA}$	1.4 V	1	V
	$I_{OH} = -8 \text{ mA}$	1.65 V	1.2	
	$I_{OH} = -9 \text{ mA}$	2.3 V	1.8	
	I <sub>OL</sub> = 100 μA	0.8 V to 2.7 V	0.2	
	I <sub>OL</sub> = 0.7 mA	0.8 V	0.25	
N/	$I_{OL} = 3 \text{ mA}$	1.1 V	0.3	V
V <sub>OL</sub>	$I_{OL} = 5 \text{ mA}$	1.4 V	0.4	V
	$I_{OL} = 8 \text{ mA}$	1.65 V	0.45	
	I <sub>OL</sub> = 9 mA	2.3 V	0.6	
I <sub>I</sub> All inp	uts $V_1 = V_{CC}$ or GND	0 to 2.7 V	±5	μA
l <sub>off</sub>	$V_{I}$ or $V_{O}$ = 2.7 V	0	±10	μΑ
I <sub>OZ</sub> <sup>(2)</sup>	$V_{O} = V_{CC}$ or GND	2.7 V	±10	μΑ
I <sub>CC</sub>	$V_{I} = V_{CC} \text{ or GND}, \qquad I_{O} = 0$	0.8 V to 2.7 V	20	μA
C <sub>i</sub>	$V_{I} = V_{CC} \text{ or } GND$	2.5 V	2.5 3	pF
C <sub>io</sub>	$V_{O} = V_{CC}$ or GND	2.5 V	7.5 8	pF

(1) (2)

All typical values are at  $T_A = 25^{\circ}C$ . For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current.

### **Switching Characteristics**

over recommended operating free-air temperature range,  $C_L = 15 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 0.8 V	V <sub>CC</sub> = ± 0.	1.2 V 1 V	V <sub>CC</sub> = ± 0.			<sub>c</sub> = 1.8 0.15 V		V <sub>CC</sub> = ± 0.		UNIT
		(INFOT)	(001F01)	TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
tŗ	pd	A or B	B or A	5	1	3.2	0.6	2	0.5	1	1.7	0.4	1.4	ns
te	en	OE	A or B	9	1.2	4.9	1	3	0.8	1.2	2.4	0.6	1.8	ns
to	dis	OE	A or B	9.5	1.9	5.7	1.2	4	0.9	1.9	4.1	0.6	2.9	ns

## **Switching Characteristics**

over recommended operating free-air temperature range,  $C_L = 30 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	۷ <sub>c</sub>	<sub>C</sub> = 1.8 \ 0.15 V	V	V <sub>CC</sub> = 1 ± 0.2	2.5 V 2 V	UNIT
	(INFUT)	(001901)	MIN	TYP	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	B or A	0.6	1.3	2.2	0.5	1.8	ns
t <sub>en</sub>	OE	A or B	1.1	1.5	3	1.1	2.4	ns
t <sub>dis</sub>	ŌĒ	A or B	1.6	2.2	4	0.8	2.6	ns

## **Operating Characteristics**

 $T_A = 25^{\circ}C$ 

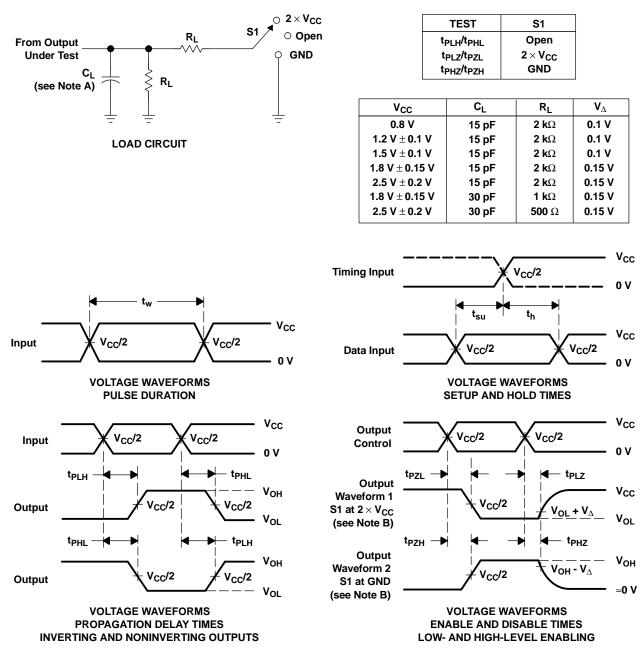
PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 0.8 V TYP	V <sub>CC</sub> = 1.2 V TYP	V <sub>CC</sub> = 1.5 V TYP	V <sub>CC</sub> = 1.8 V TYP	V <sub>CC</sub> = 2.5 V TYP	UNIT	
6	Power	Outputs enabled	f 10 MU-	20	21	21	23	27	~ [
C <sub>pd</sub>	dissipation capacitance	Outputs disabled	f = 10 MHz	1	1	1	1	1	pF

## SN74AUC245 OCTAL BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCES419A-JANUARY 2003-REVISED MARCH 2005

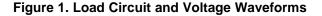


#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , slew rate  $\geq$  1 V/ns. D. The outputs are measured one at a time, with one transition per measurement.
- D. The outputs are measured one at a
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ . F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.



### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AUC245GQNR	ACTIVE	VFBGA	GQN	20	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74AUC245RGYR	ACTIVE	QFN	RGY	20	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74AUC245ZQNR	ACTIVE	VFBGA	ZQN	20	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

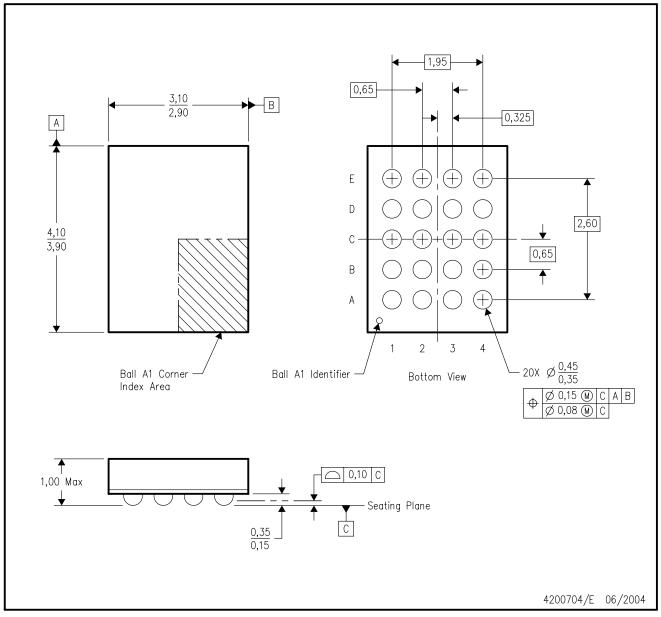
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

GQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY

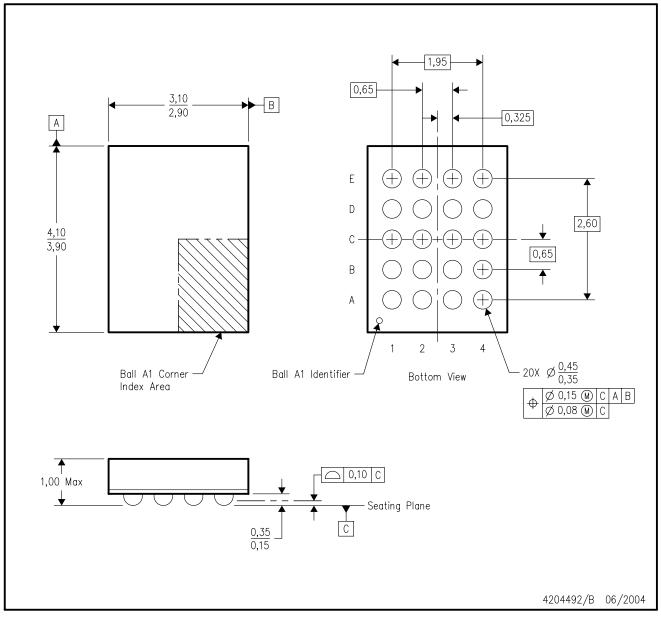


- NOTES: A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-225 variation BC.
  - D. This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.



ZQN (R-PBGA-N20)

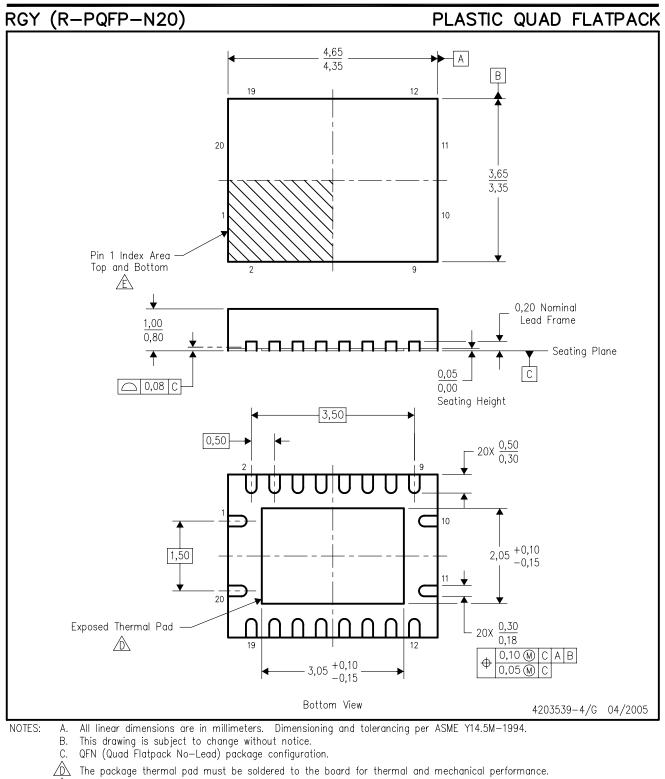
PLASTIC BALL GRID ARRAY



- NOTES: A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-225 variation BC.
  - D. This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead (SnPb).



# **MECHANICAL DATA**



- Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- F. Package complies to JEDEC MO-241 variation BC.



#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address:

Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated